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H-987

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of

A. NISHIMURA et al

Serial No. 09/869,274 ✓

Group Art Unit: 2823

Filed: June 26, 2001

Examiner: W. Coleman

For: SEMICONDUCTOR INTEGRATED CIRCUIT DEVICE HAVING BUMP
ELECTRODES FOR SIGNAL OR POWER ONLY, AND TESTING PADS
THAT ARE NOT COUPLED TO BUMP ELECTRODES (As Amended)

RESPONSE TO DRAWING OBJECTION

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Attached to the Notice of Allowability mailed March 31, 2004 was a drawing objection in which the Examiner stated that the drawings did not show a testing pad which is not coupled to any protruding electrode bump.

In reply, the Applicants refer the Examiner to Figure 51, and the corresponding passage in the specification on page 99, lines 6-16, as an example of such a testing pad. Reference numeral 209b refers to testing pads which are for bonding pads 202b dedicated for probe testing. Note that the testing pads 209b are not connected to any protruding electrodes 208.

Drawing objection withdrawn
OC
8/25/2004